

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all previous version or listings of the claims:

Listing of Claims

Claims 1-3. Cancelled.

Claim 4 (Currently amended): A manufacturing method of a multilayer printed wiring board in which at the time of manufacturing each layer of a build-up board composed of a multilayer printed wiring board with an Interstitial Via Hole (IVH) structure ~~includes~~ comprising the steps of:

bonding a metallic foil having electrical conductivity on one side of a sheet-like support substrate wherein said support substrate supports said metallic foil;

after bonding, forming metallic conductor pieces for said via holes by patterning said metallic foil;

~~forming patterns in said metallic foil;~~

transferring said metallic conductor pieces to a sheet-like insulating resin by laminating said metallic conductor pieces with said sheet-like insulating resin; and exfoliating said support substrate.

Claim 5 (Previously presented): The manufacturing method of a multilayer printed wiring board according to claim 4, further comprising roughening at least the surface of said metallic conductor pieces in contact with said insulating resin.

Claim 6 (Previously presented): The manufacturing method of a multilayer printed wiring board according to claim 4 further comprising coating said metal conductor pieces with a low-temperature diffusion metal.